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cont signal processing circuit substrate, the mounting member being fixed at opposite thereof onto the first surface of the signal processing circuit substrate.--

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Page 7, replace the last paragraph, spanning pages 7-8, as follows:

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Q2 --There is further provided a signal processing circuit substrate used for a liquid crystal display unit, a device being mounted on a first surface of the signal processing circuit substrate, the device having a variable value and including an value adjustment portion through which the variable value is adjusted, the signal processing circuit substrate being formed with a through-hole, the signal processing circuit substrate including a flexible arch-shaped member having a height relative to the first surface of the signal processing circuit substrate, the device being electrically and mechanically fixed onto a lower surface of the member in a floating condition above the signal processing circuit substrate such that the value adjustment portion is in alignment with the through-hole so as to allow the value adjustment portion to be adjusted through the through-hole, the member being fixed at opposite edges onto the first surface of the signal processing circuit substrate.--

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Page 9, replace the last two paragraphs as follows:

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23 --In another aspect of the present invention, there is provided a method of fabricating a signal processing circuit substrate used for a liquid crystal display unit, a device being mounted on a first surface of the signal processing circuit substrate, the device having a variable value and including an value adjustment portion through which the variable value is adjusted, the method including the steps of (a) mounting the device onto an upper surface of a flexible member such that the value adjustment portion upwardly faces, (b) bending the flexible member at first lines thereof towards the lower surface, (c) bending the flexible member at second lines towards the upper surface, the second lines being located between the device and the first lines, and (d) fixing the flexible member at its opposite ends onto the first surface of the signal processing circuit substrate such that the value adjustment portion is exposed through a through-hole formed through the signal processing circuit substrate.

The method may further include the step of (e) fixing a reinforcing plate onto a lower surface of the flexible member, the step (e) being carried out before the step (d).--

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Page 10, replace the last paragraph, spanning pages 10-11, as follows:

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ay --There is further provided a method of fabricating a signal processing circuit substrate used for a liquid crystal display unit, a device being mounted on a first surface of the signal processing circuit substrate, the device having a variable value and including an value adjustment portion through which the variable value is adjusted, the method including the steps of (a) patterning a flexible printed circuit sheet into patterns which will make flexible printed circuits, (b) covering the flexible printed circuit sheet with an electrical insulator, (c) mounting the device on a second surface of the flexible printed circuit sheet, (d) cutting the flexible printed circuit sheet into flexible printed circuits, (e) downwardly bending the flexible printed circuit sheet at first lines across the device, (f) upwardly bending the flexible printed circuit sheet at second lines across the device, the second lines being located between the device and the first lines, and (g) fixing the flexible printed circuit sheet onto the first surface of the signal processing circuit substrate such that the value adjustment portion of the device is in alignment with a through-hole formed throughout the signal processing circuit substrate.--

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